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- Low Offset . . . 3 mV (Max) for A-Grade
- Wide Gain-Bandwidth Product . . . 4 MHz
- High Slew Rate . . . 13 V/μs
- Fast Settling Time . . . 1.1 μs to 0.1%
- Wide-Range Single-Supply Operation ... 4 V to 36 V
- Wide Input Common-Mode Range Includes Ground (V_{CC})
- Low Total Harmonic Distortion . . . 0.02%
- Large-Capacitance Drive Capability
 ... 10,000 pF
- Output Short-Circuit Protection
- Alternative to MC33074/A and MC34074/A

description/ordering information

1OUT [1 14] 4OUT 1IN- [2 13] 4IN1IN+ [3 12] 4IN+ V_{CC+} [4 11] V_{CC}_/GND 2IN+ [5 10] 3IN+ 2IN- [6 9] 3IN2OUT [7 8] 3OUT

D, N, OR PW PACKAGE (TOP VIEW)

ORDERING INFORMATION

TA	V _{IO} max AT 25°C	PACKA	GE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
		PDIP (N)	Tube of 25	TL3474ACN	TL3474ACN
	l	SOIC (D)	Tube of 50	TL3474ACD	TL3474A
	A-grade: 3 mV	SOIC (D)	Reel of 2500	TL3474ACDR	1L3474A
	O IIIIV	TSSOP (PW)	Tube of 90	TL3474ACPW	T3474A
0°C to 70°C		1330P (PW)	Reel of 2000	TL3474ACPWR	13474A
0 0 10 70 0		PDIP (N)	Tube of 25	TL3474CN	TL3474CN
		SOIC (D)	Tube of 50	TL3474CD	TL3474C
	Standard grade: 10 mV	30IC (D)	Reel of 2500	TL3474CDR	1134740
		TSSOP (PW)	Tube of 90	TL3474CPW	TL3474
		1330P (PW)	Reel of 2000	TL3474CPWR	113474
	A-grade: 3 mV	PDIP (N)	Tube of 25	TL3474AIN	Z3474A
		SOIC (D)	Tube of 50	TL3474AID	TL3474AI
		SOIC (D)	Reel of 2500	TL3474AIDR	TL3474AI
		TSSOP (PW)	Tube of 90	TL3474AIPW	Z3474A
-40°C to 105°C		1330P (PW)	Reel of 2000	TL3474AIPWR	Z3474A
-40°C to 105°C		PDIP (N)	Tube of 25	TL3474IN	TL3474IN
	.	SOIC (D)	Tube of 50	TL3474ID	TL3474I
	Standard grade: 10 mV	3010 (D)	Reel of 2500	TL3474IDR	1 L34/41
	101111	TSSOR (DW)	Tube of 90	TL3474IPW	Z3474
		TSSOP (PW)	Reel of 2000	TL3474IPWR	Z34/4

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

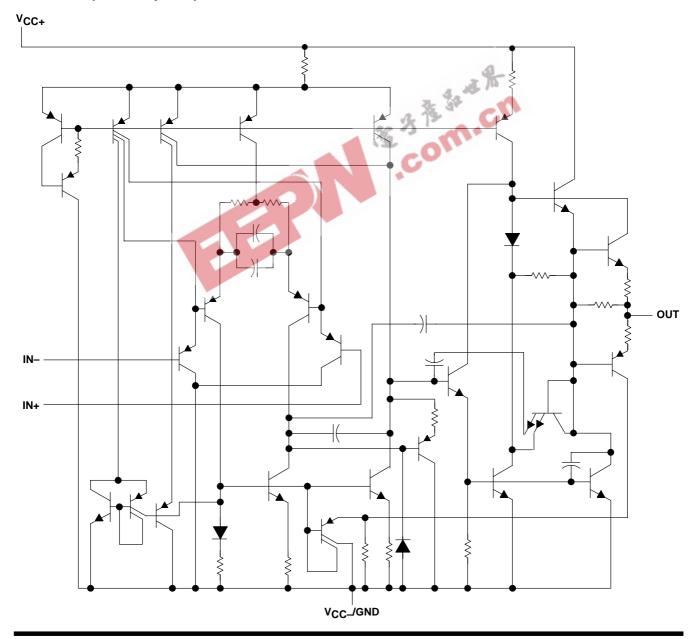


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description/ordering information (continued)

Quality, low-cost, bipolar fabrication with innovative design concepts is employed for the TL3474, TL3474A operational amplifiers. These devices offer 4 MHz of gain-bandwidth product, 13-V/ μ s slew rate, and fast settling time without the use of JFET device technology. Although the TL3474 and TL3474A can be operated from split supplies, they are particularly suited for single-supply operation because the common-mode input voltage range includes ground potential (V_{CC}). With a Darlington transistor input stage, these devices exhibit high input resistance, low input offset voltage, and high gain. The all-npn output stage, characterized by no dead-band crossover distortion and large output voltage swing, provides high-capacitance drive capability, excellent phase and gain margins, low open-loop high-frequency output impedance, and symmetrical source/sink ac frequency response. These low-cost amplifiers are an alternative to the MC34074/A and MC33074/A operational amplifiers.

schematic (each amplifier)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Cumply voltage: V (and Note 1)	40 \/
Supply voltage: V _{CC+} (see Note 1)	10 V
V _{CC}	–18 V
Differential input voltage, V _{ID} (see Note 2)	±36 V
Input voltage, V _I (any input)	V _{CC±}
Input current, I _I (each input)	±1 mA
Output current, IO	±80 mA
Total current into V _{CC+}	80 mA
Total current out of V _{CC}	
Duration of short-circuit current at (or below) 25°C (see Note 3)	Unlimited
Package thermal impedance, θ _{JA} (see Notes 4 and 5): D package	86°C/W
N package	80°C/W
PW package	113°C/W
Operating virtual junction temperature, T _J	
Lead temperature 1.6 mm (1/16 inch) from case for 10 seconds	
Storage temperature range, T _{stq}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential voltages, are with respect to the midpoint between V_{CC+} and V_{CC}_/GND.
 - 2. Differential voltages are at the noninverting input with respect to the inverting input. Excessive input current can flow when the input is less than V_{CC} 0.3 V.
 - 3. The output can be shorted to either supply. Temperature and/or supply voltages must be limited to ensure that the maximum dissipation rating is not exceeded.
 - Maximum power dissipation is a function of T_J(max), θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is P_D = (T_J(max) T_A)/θ_{JA}. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 5. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

					MIN	MAX	UNIT	
V _{CC±}	Supply voltage				4	36	V	
Via Common mode		ut voltage		V _{CC} = 5 V	0	2.8	V	
VIC	Common-mode inp	Common-mode input voltage				12.8	v	
т.	Operating free air temperature		_	TL3474C, TL3474AC	0	70	°C	
TA	Operating free-air temperature TL3474I, TL3474AI					105		

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electrical characteristics at specified free-air temperature, $V_{\text{CC}\pm}$ = ± 15 V (unless otherwise noted)

	ARAMETER	TEST CONDITIONS		+		TL3474			TL3474A					
I ANAMETEN		TEST COND	TA	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT				
			V _{CC} = 5 V	25°C		1.5	10		1.5	3				
V_{IO}	Input offset voltage		V _{CC} = ±15 V	25°C		1.0	10		1.0	3	mV			
	Tenage		VCC = ±13 V	Full range‡			12			5				
α۷ιΟ	Temperature coefficient of input offset voltage	V _{IC} = 0, V _O = 0,	V _{CC} = ±15 V	Full range‡		10			10		μV/°C			
1	Input offset	$R_S = 50 \Omega$	V 145 V	25°C		6	75		6	75	Λ			
ΙΟ	current		$V_{CC} = \pm 15 \text{ V}$	Full range‡			300			300	nA			
lin	Input bias current		V _{CC} = ±15 V	25°C		100	500		100	500	nA			
IΒ	input bias current		VCC = ±13 V	Full range‡			700			700	ΠA			
Common-mode		Rs = 50 Ω		25°C		–15 to 12.8			–15 to 12.8		٧			
VICR input voltage range	11.5 = 00 32	Full range‡		-15 to 12.8	8		–15 to 12.8		•					
\/-··	High-level VOH output voltage	$V_{CC+} = 5 \text{ V}, V_{CC-} = R_L = 2 \text{ k}\Omega$	25°C	3.7	4	c_{L}	3.7	4		V				
۷ОН		$R_L = 10 \text{ k}\Omega$	25°C	13.6	14		13.6	14						
		$R_L = 2 k\Omega$	Full range‡	13.4	13.4									
., Low-level		$V_{CC+} = 5 \text{ V}, V_{CC-} = R_L = 2 \text{ k}\Omega$	25°C		0.1	0.3		0.1	0.3	V				
VOL	output voltage	$R_L = 10 \text{ k}\Omega$	25°C		-14.7	-14.3		-14.7	-14.3	V				
		$R_L = 2 k\Omega$	Full range‡			-13.5			-13.5	5				
A_{VD}	Large-signal differential	$V_O = \pm 10 \text{ V}, R_L = 2 \text{ k}\Omega$		25°C	25	100		25	100		V/mV			
VD	voltage amplification			Full range‡	20			20						
los	Short-circuit	Source: V _{ID} = 1 V,	25°C	-10	-34		-10	-34		mA				
.03	output current	Sink: $V_{ID} = -1 V$,		20	27		20	27						
CMRR	Common-mode rejection ratio	$V_{IC} = V_{ICR}(min),$	$R_S = 50 \Omega$	25°C	65	97		80	97		dB			
ksvr	Supply-voltage rejection ratio (ΔV _{CC±} /ΔV _{IO})	$V_{CC\pm} = \pm 13.5 \text{ V to } \pm R_S = 100 \Omega$	16.5 V,	25°C	70	97		70	97		dB			
		V _O = 0,	No load	25°C		3.5	4.5		3.5	4.5				
Icc	Supply current	v () = 0,	INU IUAU	Full range‡		4.5	5.5		4.5	5.5	mA			
.00	(per channel)	$V_{CC+} = 5 \text{ V}, V_{O} = 2.$ $V_{CC-} = 0, \text{ No load}$.5 V,	25°C		3.5	4.5		3.5	4.5				

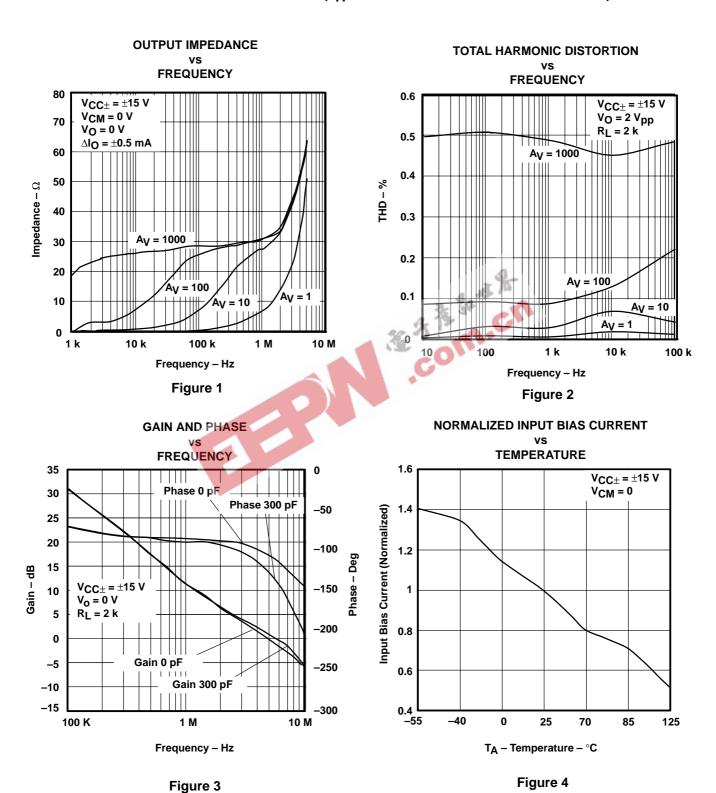
[†] All typical values are at T_A = 25°C. ‡ Full range is 0°C to 70°C for the TL3474C, TL3474AC devices and –40°C to 105°C for the TL3474I, TL3474AI devices.

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operating characteristics, $V_{CC\pm}$ = ± 15 V, T_A = $25^{\circ}C$

DADAMETED		TEST SOMBITIO	TL3474			TL3474A				
	PARAMETER	TEST CONDITION	MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
SR+	Positive slew rate	$V_{I} = -10 \text{ V to } 10 \text{ V},$	A _V = 1	8	10		8	10		VIII
SR-	Negative slew rate	$R_L = 2 k\Omega$, $C_L = 300 pF$	A _V = -1		13			13		V/μs
t _S	Settling time	A _{VD} = -1, 10-V step	To 0.1%		1.1			1.1		μs
Vn	Equivalent input noise voltage	f = 1 kHz,	To 0.01% $R_S = 100 Ω$		49			49		nV/√ Hz
In	Equivalent input noise current	f = 1 kHz	0.22			0.22			pA/√ Hz	
THD	Total harmonic distortion	$V_{O(PP)} = 2 \text{ V to } 20 \text{ V, R}_{L} = A_{VD} = 10, f = 10 \text{ kHz}$	0.02			0.02			%	
GBW	Gain-bandwidth product	f =100 kHz		3	4		3	4		MHz
BW	Power bandwidth	$V_{O(PP)} = 20 \text{ V, R}_{L} = 2 \text{ k}\Omega,$ $A_{VD} = 1, \text{ THD} = 5.0\%$			160			160		kHz
_	Phase margin	$R_L = 2 k\Omega$,	C _L = 0		70			70		deg
φm	Friase margin	$R_L = 2 k\Omega$,	50			50			ueg	
	Gain margin	$R_L = 2 k\Omega$, $C_L = 0$		12			12			dB
	Gairmargin	$R_L = 2 k\Omega$, $C_L = 300 pF$		4		4		GD.		
rį	Differential input resistance	V _{IC} = 0	C	0,,	150			150		МΩ
Ci	Input capacitance	V _{IC} = 0			2.5			2.5		pF
	Channel separation	f = 10 kHz			101			101		dB
z ₀	Open-loop output impedance	f = 1 MHz,	A _V = 1		20	_		20		Ω

TYPICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ UNLESS OTHERWISE NOTED)





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TYPICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ UNLESS OTHERWISE NOTED)

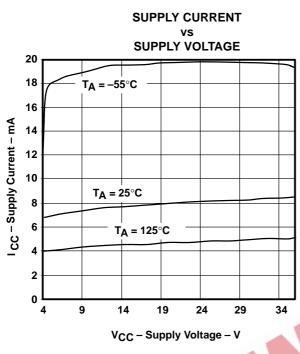


Figure 5

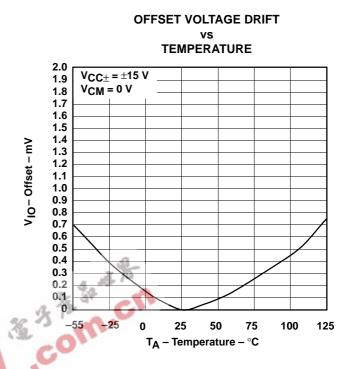


Figure 6

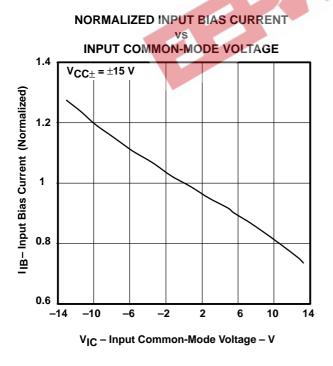


Figure 7

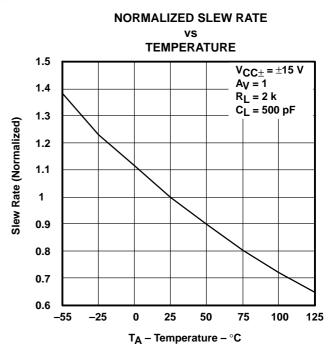
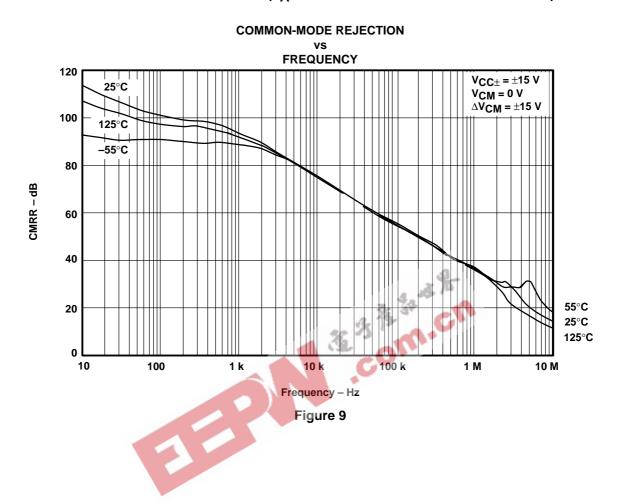


Figure 8

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TYPICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ UNLESS OTHERWISE NOTED)







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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TL3474ACD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474ACDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474ACDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474ACDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474ACN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL3474ACNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL3474ACPW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474ACPWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474ACPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474ACPWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474AID	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474AIDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474AIDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474AIDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474AIDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474AIDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474AIN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL3474AINE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL3474AIPW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474AIPWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474AIPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474AIPWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474CD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474CDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474CDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM



PACKAGE OPTION ADDENDUM

17-Oct-2005

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp (3)
TL3474CDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474CN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL3474CNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL3474CPW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474CPWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474CPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474CPWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474ID	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474IDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474IDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474IDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474IN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL3474INE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL3474IPW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474IPWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474IPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3474IPWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

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⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



PACKAGE OPTION ADDENDUM

17-Oct-2005

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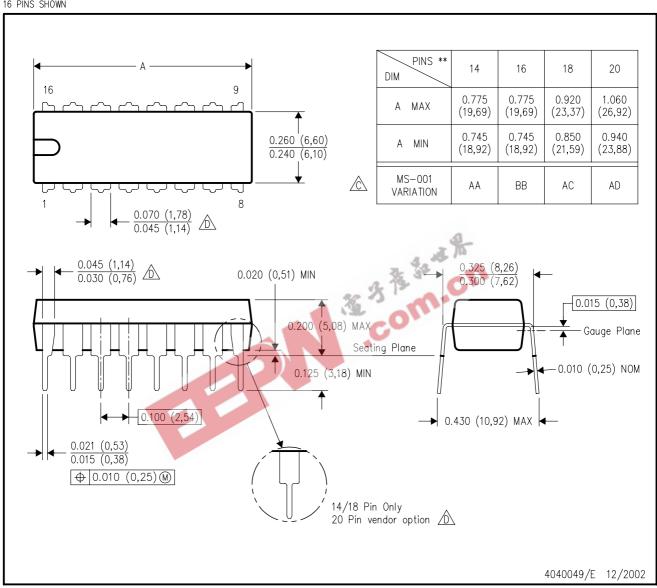
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N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

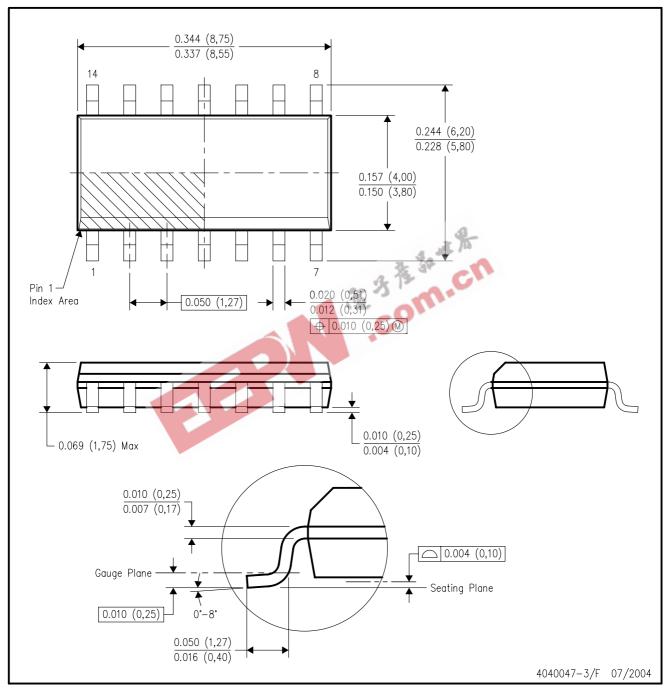


NOTES:

- All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

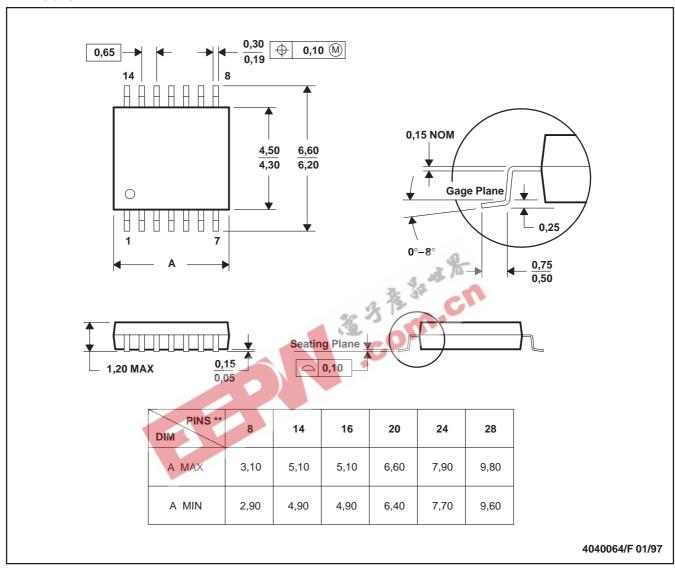
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.



PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
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